IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Bruno GHYSELEN et al.

Application No.: Group Art Unit:

Filing Date: Concurrently herewith Examiner:

For: PROCESS FOR TRANSFERRING A Attorney Docket No.: 4717-7500

LAYER OF STRAINED

SEMICONDUCTOR MATERIAL

INFORMATION DISCLOSURE STATEMENT

MS PATENT APPLICATION

Commissioner for Patents Washington, D.C. 20231

Sir:

Pursuant to Applicant's duty of disclosure under 37 C.F.R. § 1.56, enclosed are copies of sixteen (16) references listed on the enclosed Form PTO-1449 for the Examiner's review. Also enclosed is a copy of the preliminary International Search Report from the French priority application on which some of the references were cited. It is respectfully requested that the references be made of record in this application by the Examiner's completion and return of the attached Form PTO-1449.

No fee is believed to be due for the submission of the these references. Should any fees be required, however, please charge such fees to Winston & Strawn Deposit Account No. 501-814.

Respectfully submitted,

July 9, 2003

E. Bradley Gould

E. Bradley Gould (Reg. No. 41,792) For: Allan A Fanucci (Reg. No. 30,256)

WINSTON & STRAWN Customer No. 28765

202-371-5771

LIS	ST OF	REFERENCES CIT	ATTY. DOCKET NO.: 4717-7500 APPLICANT:	APPLICATION NO.:					
		(Use several sheets i	Bruno GHYSELEN et al.						
Sheet 1 of 1					FILING DATE:		GROUP:		
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			U.S. F	PATENT DOC	UMENTS	· •			
*EXAMINER INITIAL	CITE NO.	DOCUMENT NUMBER	DATE	NAME		CLASS	SUBCLASS	S FILING DATE IS APPROPRIATE	
	Α	6,573,126	06/2003	Cheng et al.		438	149		
	В	6,524,935	02/2003	Canaperi et al.		438	478		
	С	6,410,371	06/2002	Yu et al.		438	151		
	D	6,403,450	06/2002	Maleville et al.		438	471	/1	
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	J	01/99169	12/2001	WO		 			
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<u> </u>		OTHER REFER	ENCES (Inc	luding Author, I	Title, Date, Pertinent F	Pages, Etc.,)		<u>L</u>
	L	L.J. Huang et al., SiGe-On-Insulator Prepared by Wafer Bonding and Layer Transfer for High Performance Field-Effect Transistors, Applied Physics Letters, February 26, 2002, Vol 78, No. 9							
	М	Zhi-Yuan Cheng et al. of Massachusetts Institute of Technology has presented, in a document entitled SiGe-On-Insulator (SGOI): Substrate Preparation and MOSFET Fabrication for Electron Mobility Evaluation (2001 IEEE International SOI Conference, 10/01)							
	N	T. A. Langdo et al., SiGe-Free Strained Si On Insulator by Wafer Bonding and Layer Transfer							
	0								
	P Patent Application Publication No. US 2002/0030227 A1, published March 14, 200 2								
EXAMINE	R				CONSIDERED				
*EXAMINE	R: and no	Initial if reference considere t considered. Include copy	ed, whether or n	ot citation is in con	formance with MPEP 609.	Draw line t	hrough citat	ion if r	not in